

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants

Reishi Naka et al.

Application No.

10/004,538

Filed

October 23, 2001

For

HEAT CONDUCTIVITY MEASUREMENT METHOD AND

INSTRUMENT AND METHOD OF PRODUCING A HEAT

INSULATING MATERIAL

Examiner

Gail Kaplan Verbitsky

Art Unit

2859

Docket No.

980039.409

Date

March 6, 2003

Commissioner for Patents Washington, DC 20231

AMENDMENT

Commissioner for Patents:

In response to the Office Action dated November 6, 2002, please extend the period of time for response one month, to expire on March 6, 2003. Enclosed are a Petition for an Extension of Time and the requisite fee. Please amend the application as follows:

In the Title:

Please amend the title to read as follows:

THERMAL CONDUCTIVITY MEASUREMENT METHOD AND INSTRUMENT AND METHOD OF PRODUCING A HEAT INSULATING MATERIAL

In the Claims:

Please amend claims 1-7 to read as follows:

(All pending claims have been provided for the convenience of the Examiner).

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03/13/2003 WABDELR1 00000047 10004538